	θ		/W
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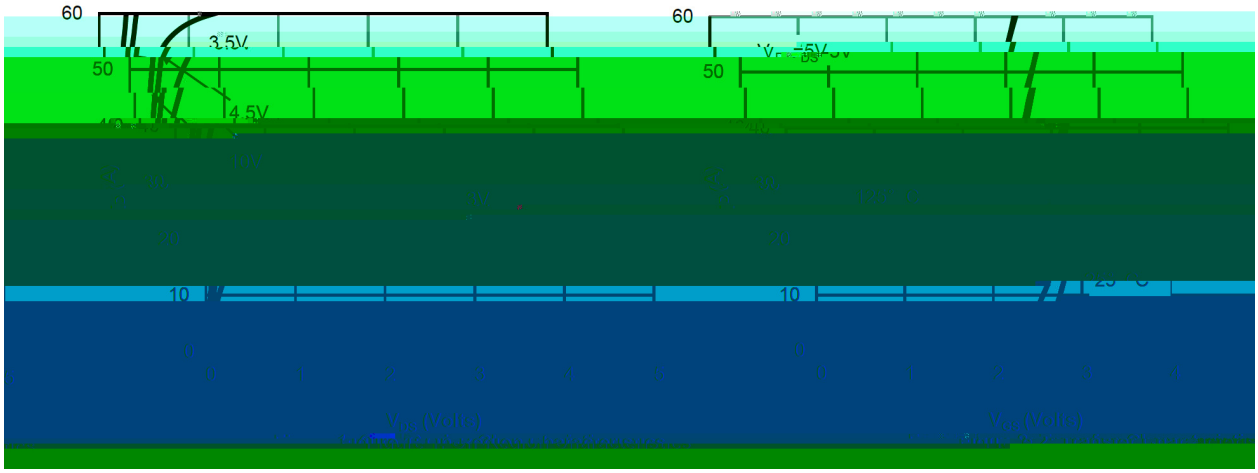
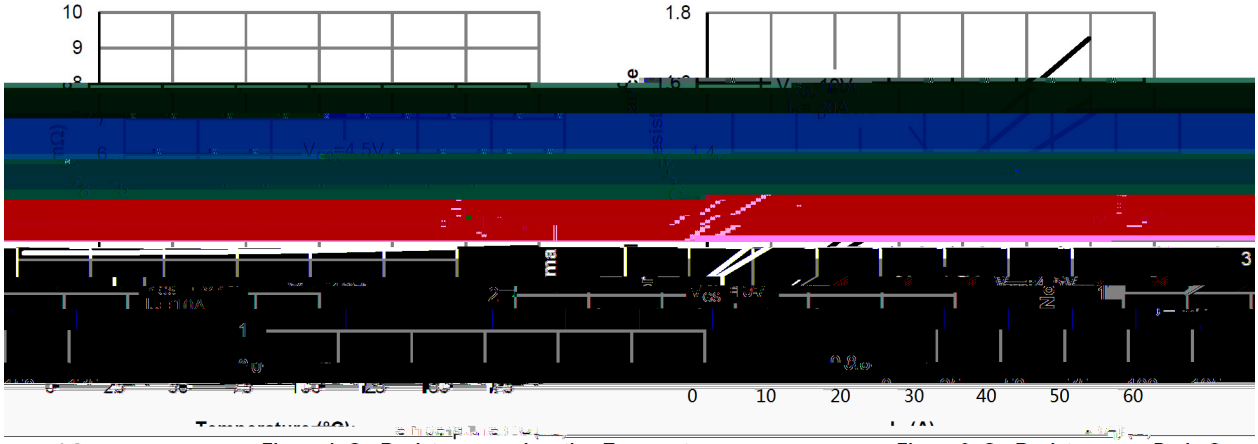
/ Electrical Characteristic Curve

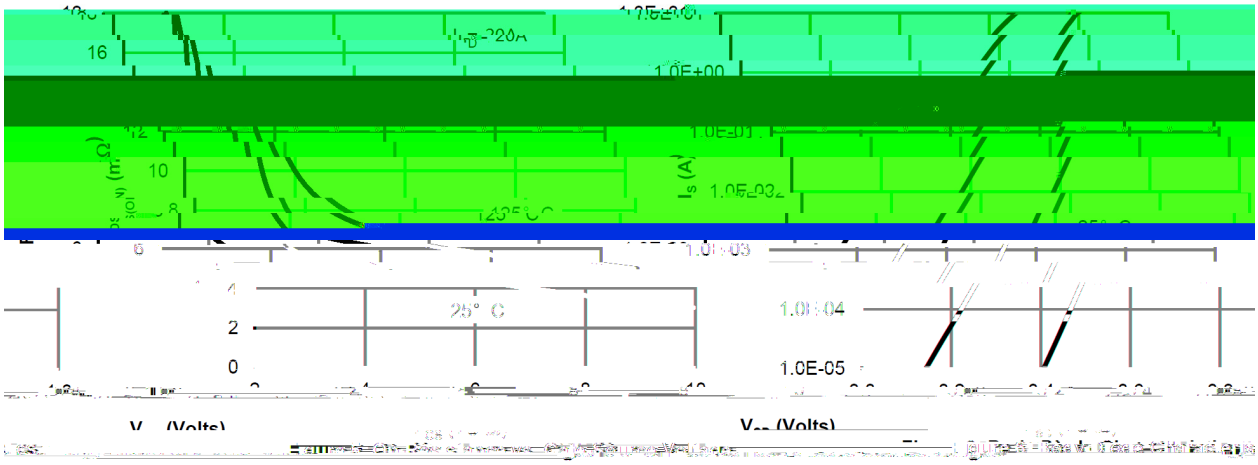




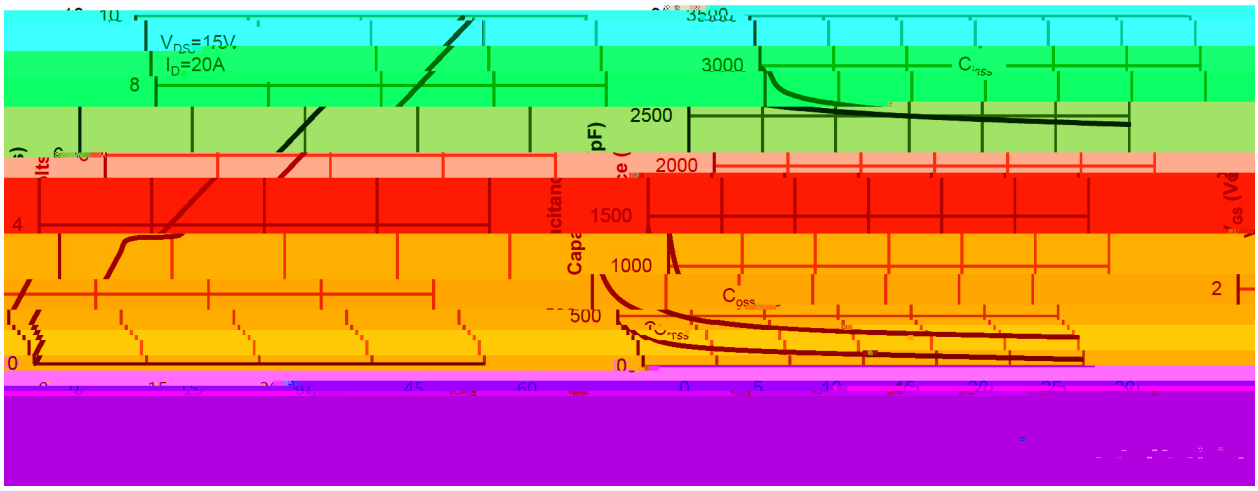
nt and Gate

Figure 4: On-Resistance vs. Junction Temperature

Figure 3: On-Resistance vs. Drain Curre Voltage



/ Electrical Characteristic Curve



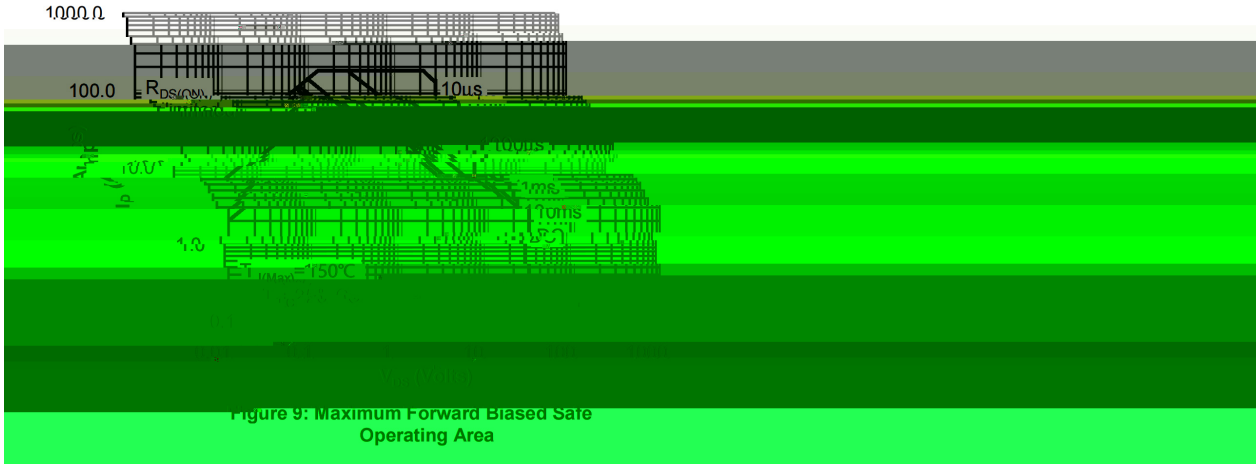
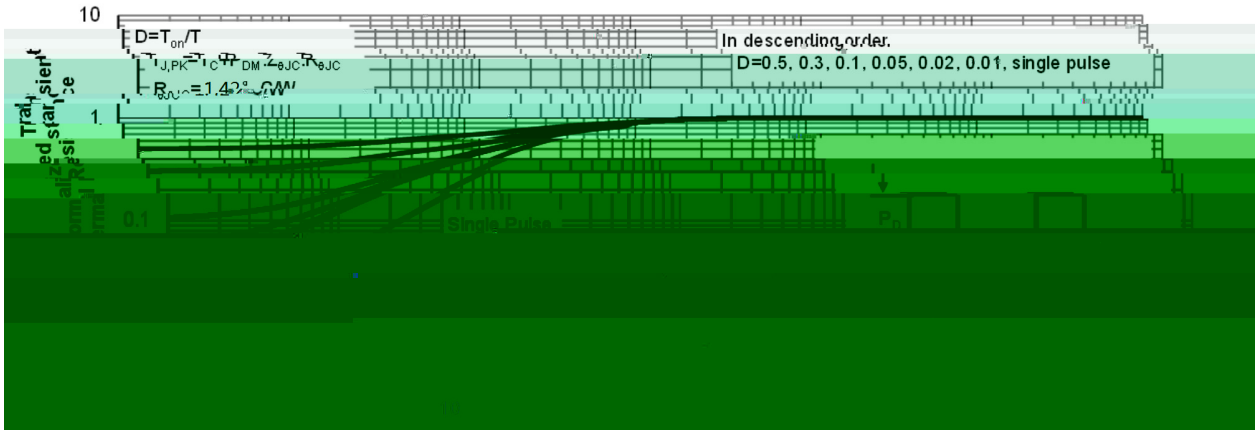
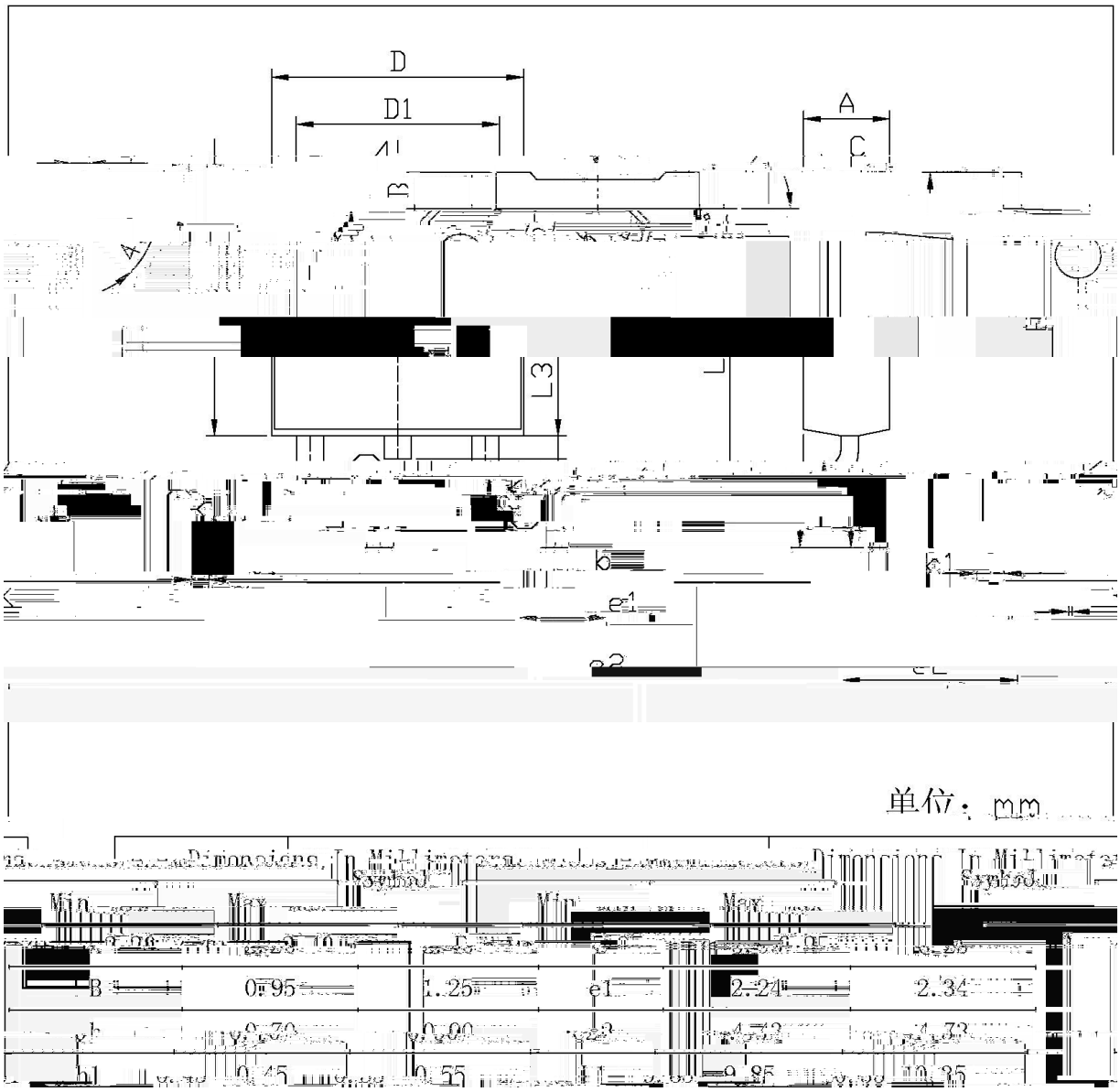


Figure 9: Maximum Forward Biased Safe Operating Area

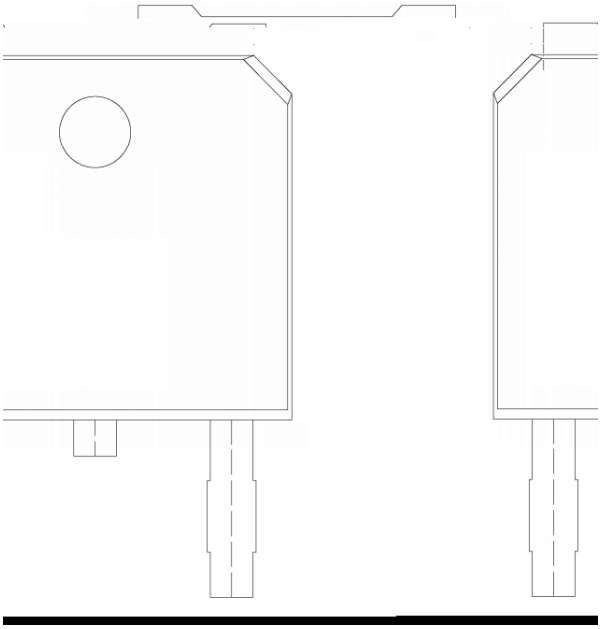


/ Package Dimensions



Symbol	Min	Max	Symbol	Min	Max
B	0.95	1.25	e1	2.24	2.34
b	0.70	0.90	e2	4.53	4.73
b1	0.45	0.55	L	9.85	10.35

/ Marking Instructions



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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.